CLAIMS

1. A method of mounting electronic parts, on a wiring board, in which a bare chip is bonded to connecting pads via thin solder layers by means of flip-chip bonding and at least another soldered part is soldered to a mounting pad on the board via a thin solder layer, said method comprising the following steps of:

a step of forming adhesive resin layers on the connecting pads and the mounting pad;

a step of scattering solder particles so that the solder particles temporarily adhere to the connecting pads and the mounting pad;

a step of putting the soldered part on the mounting pad and reflowing so that the solder particles are made to reflow to pre-coat the connecting pads with a thin solder layer and simultaneously the soldered part is mounted on the mounting pad via solder; and

a step of putting the bare chip to be positioned on the thin solder layer of the connecting pads and flip-chip bonding by which the bare chip is flip-chip bonded to the connecting pads.

2. A method as set forth in claim 1, wherein the adhesive resin layers are formed on the connecting pads and the mounting pad by dipping the board in a solution of a tackifier chemical compound.

3. A method as set forth in claim 1, wherein the adhesive resin layers are formed by coating the connecting pads and the mounting pad with a solution of a tackifier chemical compound.

4. A method as set forth in claim 1, wherein the solder particles are made of tin-silver alloy.